

TE Internal #: 2201778-1

Micro Secure Digital, 8 Position, 1.1 mm [.04 in] Centerline, Right

Angle, -30 - 105 °C [-22 - 221 °F], SD Card Connectors

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Connectors > PCB Connectors > Memory Card Connectors > SD Card Connectors











Compatible Card: Micro Secure Digital

Number of Positions: 8

Centerline (Pitch): 1.1 mm [ .04 in ]
PCB Mount Orientation: Right Angle

Operating Temperature Range: -30 - 105 °C [-22 - 221 °F]

PCB Contact Termination Area Plating Material

### **Features**

### **Product Type Features**

Connector & Contact Terminates To	Printed Circuit Board
Compatible Card	Micro Secure Digital
Configuration Features	
Number of Rows	1
Number of Positions	8
PCB Mount Orientation	Right Angle
Body Features	
Primary Product Color	Black
Contact Features	
Contact Current Rating (Max)	.5 A
Contact Underplating Material	Nickel
Contact Layout	Inline
Contact Mating Area Plating Material	Gold (Au)
Contact Base Material	Copper Alloy

Gold Flash



### **Termination Features**

Termination Method to PCB	Surface Mount
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Housing Material	LCP
Shell Material	Copper Alloy
Centerline (Pitch)	1.1 mm[.04 in]
Dimensions	
Profile Height from PCB	1.65 mm[.065 in]
Usage Conditions	
Operating Temperature Range	-30 – 105 °C[-22 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tape & Reel

## **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C



#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

### Compatible Parts



# **Customers Also Bought**

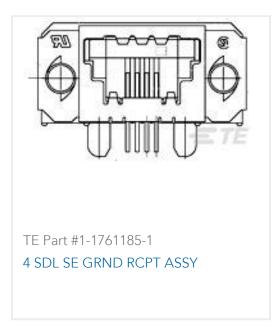




















TE Part #1977907-1 CAT5e In-Line Shielded Coupler

### **Documents**

### **Product Drawings**

MICRO SD PUSH PUSH LOW PROFILE TYPE

English

#### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_2201778-1\_A\_c-2201778-1-a.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2201778-1\_A\_c-2201778-1-a.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2201778-1\_A\_c-2201778-1-a.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

### **Product Specifications**

**Product Specification** 

English

**Product Specification** 

English